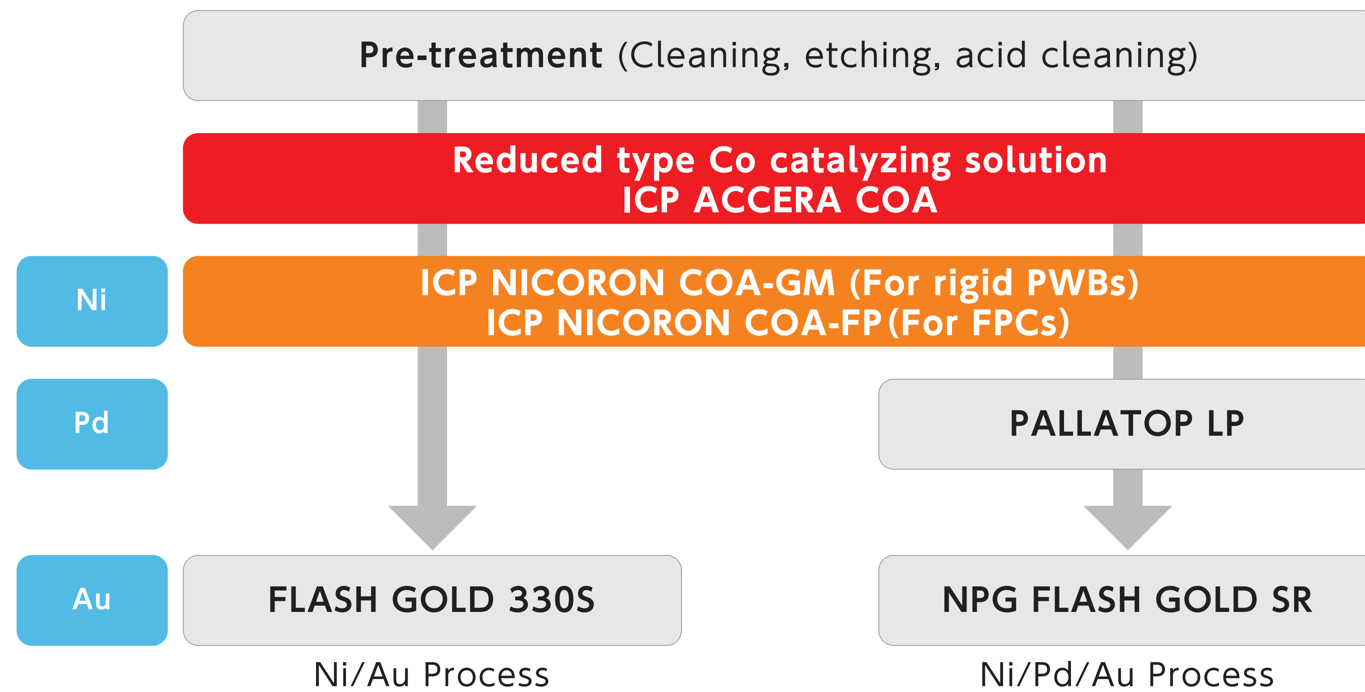
ICP-COA PROCESS

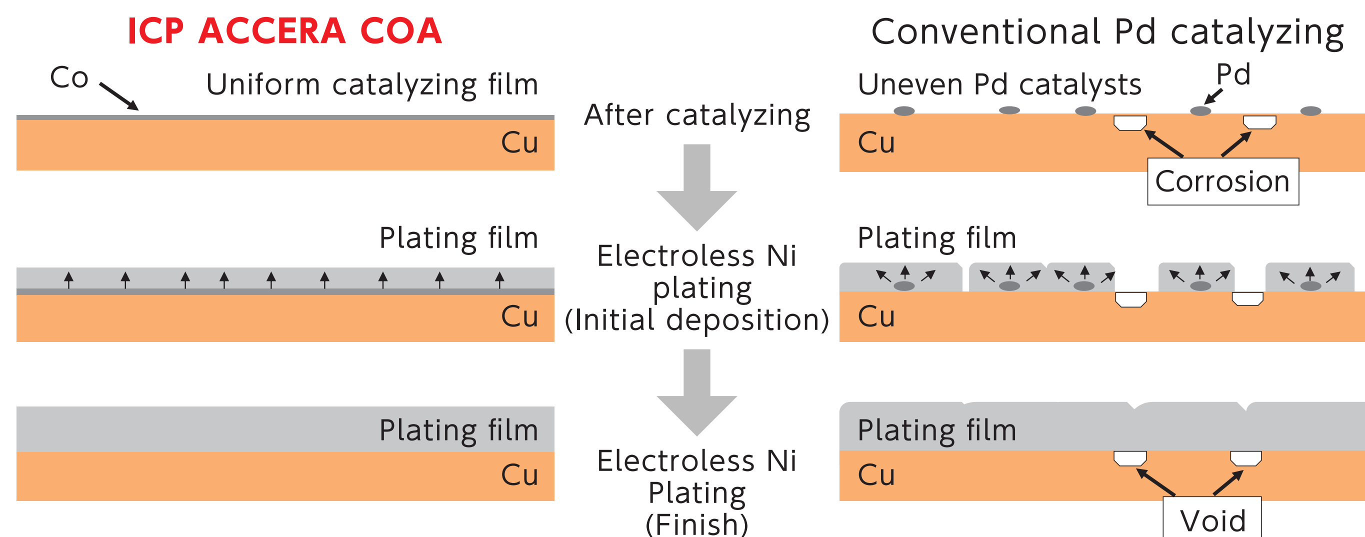
Void-free final surface treatment by reduced-type cobalt catalysts for printed wiring boards

- Use reduced-type cobalt catalysts to protect Cu substrates
- Void-free, high covering performance can be obtained
- Excellent in fine-patterning performance
- Ni/Au, Ni/Pd/Au, and applicable to various electroless plating

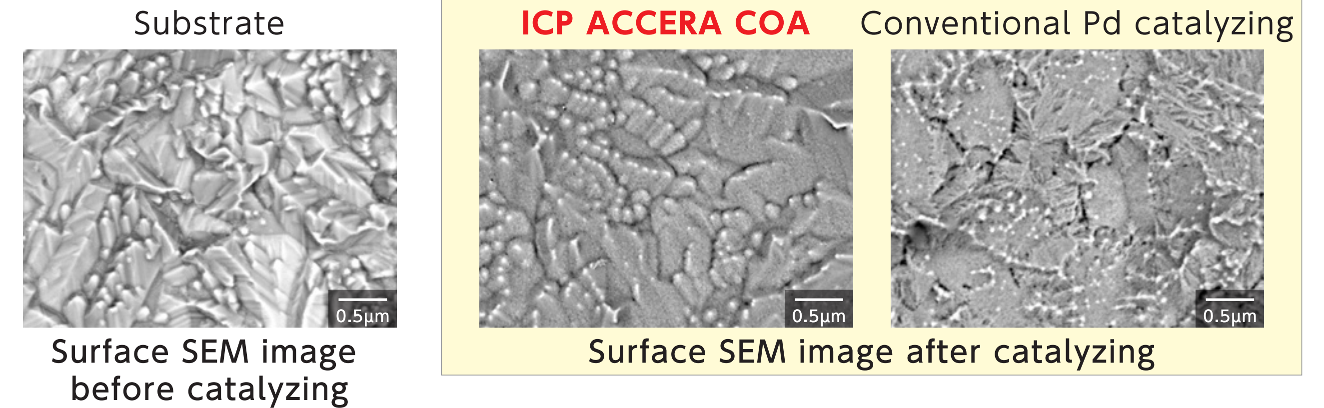
For various electroless plating process



Void-free, high covering power comes available

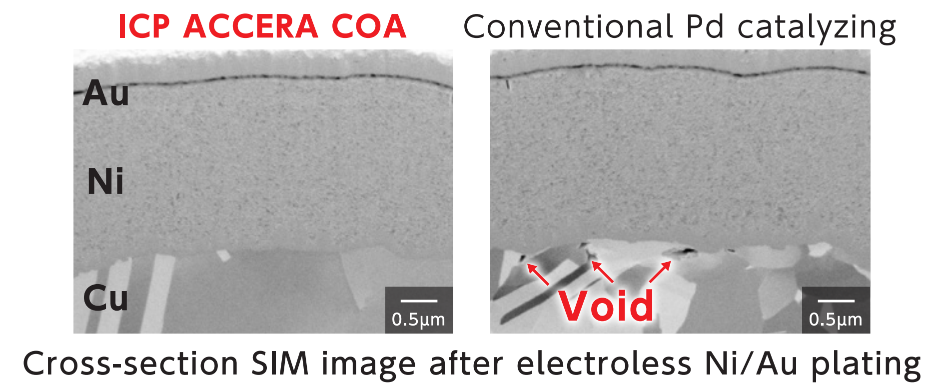


Prevent Cu corrosion at catalyzing　No void occurrence



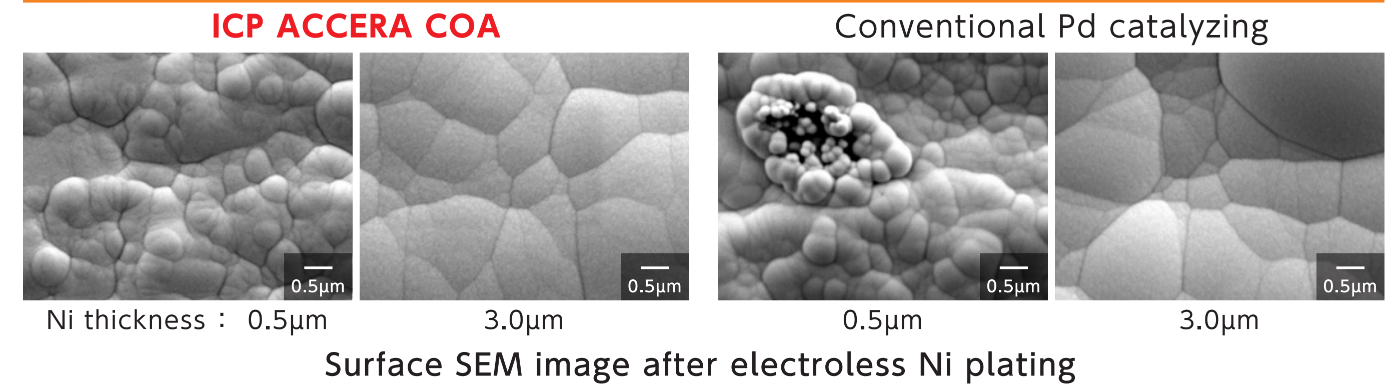
Surface SEM image before catalyzing

Surface SEM image after catalyzing



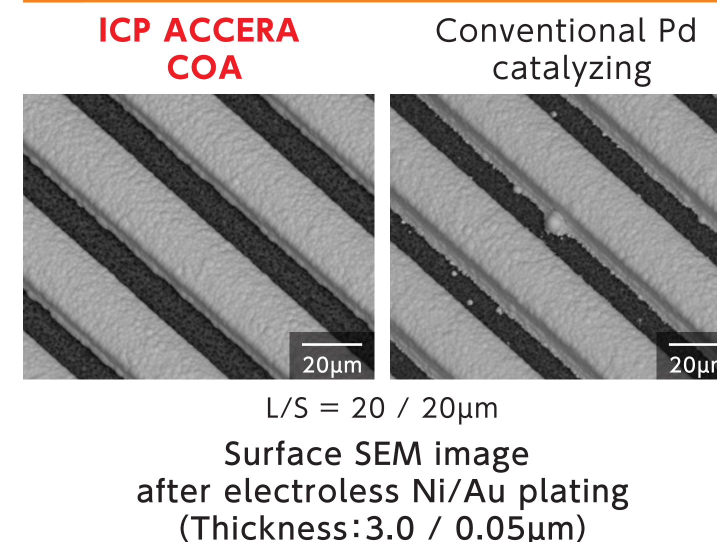
Cross-section SIM image after electroless Ni/Au plating

Fine and uniform deposition by small thickness



Surface SEM image after electroless Ni plating

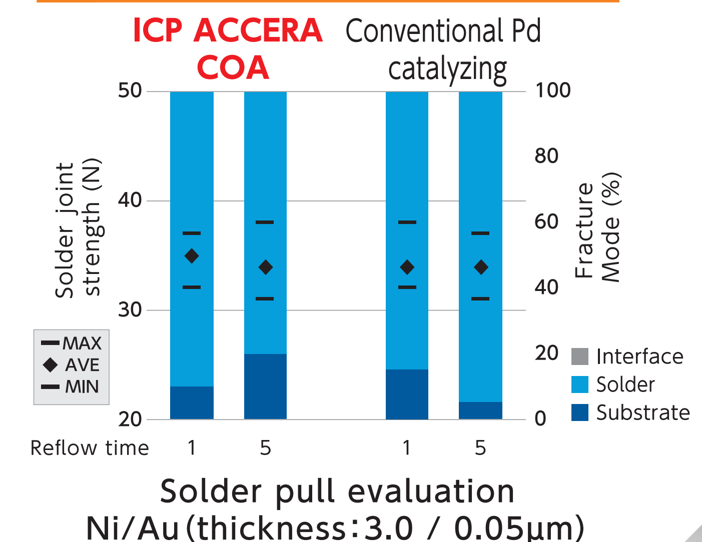
Excellent fine patterning performance



L/S = 20 / 20µm

Surface SEM image after electroless Ni/Au plating (Thickness:3.0 / 0.05µm)

Great solder joint ability



Solder pull evaluation Ni/Au (thickness:3.0 / 0.05µm)